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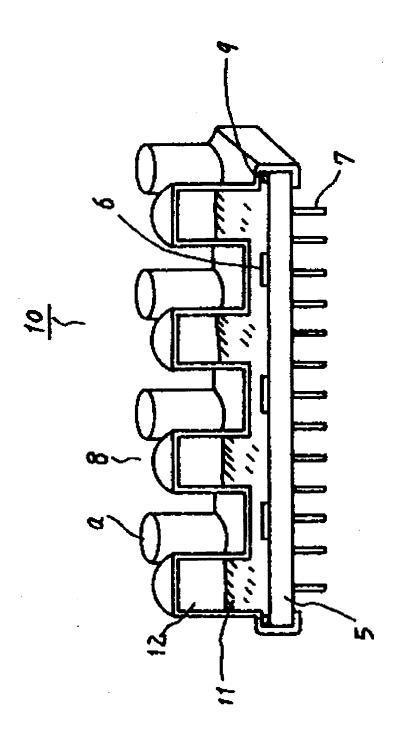
(54) EBULLITION TYPE COOLING MODULE

(57) Abstract:

PURPOSE: To form a compact and lightweight ebullition type cooling module, by using a thin container having a large number of cylindrical projections as the parts corresponding to inner and outer fins of the module.

CONSTITUTION: A substrate 5 mounted with semiconductor elements 6 and a container 8 having a large number of cylindrical projections a are sealed with each other through a packing 9 to form a cooling type module 10. A coolant 11 is enclosed in the module 10. Because the thin container having a large number of cylindrical projections is used as the parts corresponding to inner and outer fins of the module 10, it is possible to obtain a module inexpensive and excellent in cooling efficiency.

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